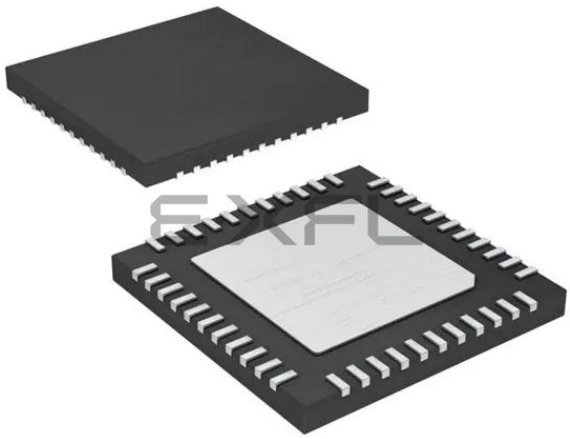
Microchip Technology - DSPIC33EP64GP504T-I/ML Datasheet



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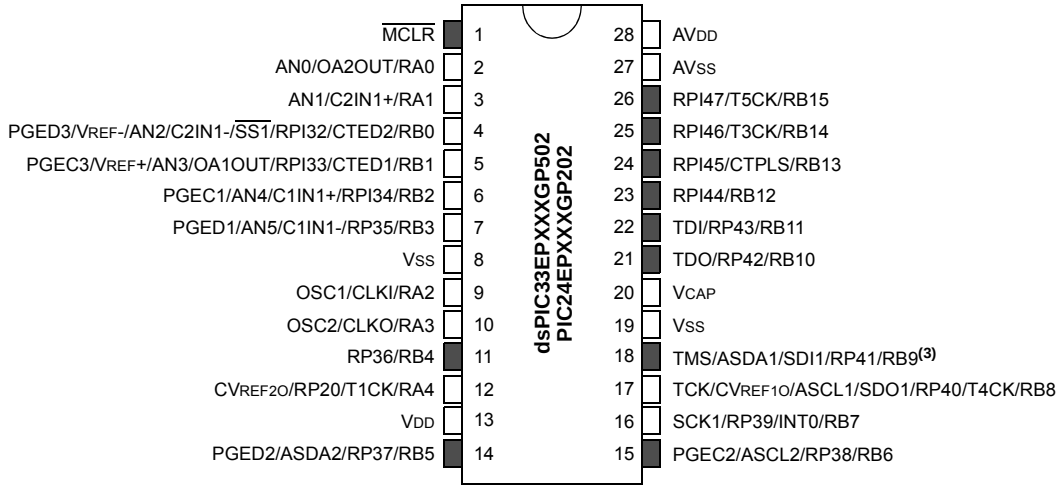
Applications of "Embedded - Microcontrollers"

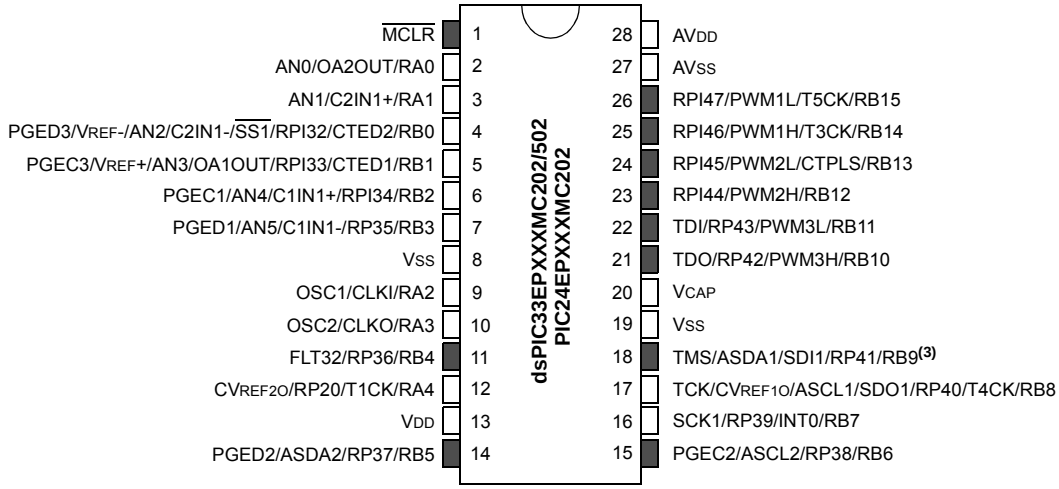
Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	35
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep64gp504t-i-ml

Pin Diagrams

28-Pin SPDIP/SOIC/SSOP(1,2)

■ = Pins are up to 5V tolerant



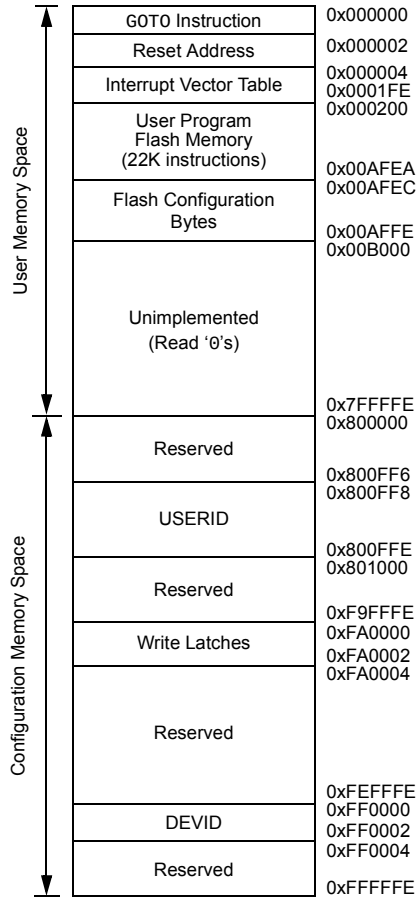


Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

FIGURE 4-2: PROGRAM MEMORY MAP FOR dsPIC33EP64GP50X, dsPIC33EP64MC20X/50X AND PIC24EP64GP/MC20X DEVICES



Note: Memory areas are not shown to scale.

TABLE 4-45: DMAC REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
DMA0CON	0B00	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000
DMA0REQ	0B02	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>								00FF
DMA0STAL	0B04	STA<15:0>																0000
DMA0STAH	0B06	—	—	—	—	—	—	—	—	STA<23:16>								0000
DMA0STBL	0B08	STB<15:0>																0000
DMA0STBH	0B0A	—	—	—	—	—	—	—	—	STB<23:16>								0000
DMA0PAD	0B0C	PAD<15:0>																0000
DMA0CNT	0B0E	—	—	CNT<13:0>														0000
DMA1CON	0B10	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000
DMA1REQ	0B12	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>								00FF
DMA1STAL	0B14	STA<15:0>																0000
DMA1STAH	0B16	—	—	—	—	—	—	—	—	STA<23:16>								0000
DMA1STBL	0B18	STB<15:0>																0000
DMA1STBH	0B1A	—	—	—	—	—	—	—	—	STB<23:16>								0000
DMA1PAD	0B1C	PAD<15:0>																0000
DMA1CNT	0B1E	—	—	CNT<13:0>														0000
DMA2CON	0B20	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000
DMA2REQ	0B22	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>								00FF
DMA2STAL	0B24	STA<15:0>																0000
DMA2STAH	0B26	—	—	—	—	—	—	—	—	STA<23:16>								0000
DMA2STBL	0B28	STB<15:0>																0000
DMA2STBH	0B2A	—	—	—	—	—	—	—	—	STB<23:16>								0000
DMA2PAD	0B2C	PAD<15:0>																0000
DMA2CNT	0B2E	—	—	CNT<13:0>														0000
DMA3CON	0B30	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000
DMA3REQ	0B32	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>								00FF
DMA3STAL	0B34	STA<15:0>																0000
DMA3STAH	0B36	—	—	—	—	—	—	—	—	STA<23:16>								0000
DMA3STBL	0B38	STB<15:0>																0000
DMA3STBH	0B3A	—	—	—	—	—	—	—	—	STB<23:16>								0000
DMA3PAD	0B3C	PAD<15:0>																0000
DMA3CNT	0B3E	—	—	CNT<13:0>														0000
DMAPWC	0BF0	—	—	—	—	—	—	—	—	—	—	—	—	PWCOL3	PWCOL2	PWCOL1	PWCOL0	0000
DMARQC	0BF2	—	—	—	—	—	—	—	—	—	—	—	—	RQCOL3	RQCOL2	RQCOL1	RQCOL0	0000
DMAPPS	0BF4	—	—	—	—	—	—	—	—	—	—	—	—	PPST3	PPST2	PPST1	PPST0	0000
DMALCA	0BF6	—	—	—	—	—	—	—	—	—	—	—	—	LSTCH<3:0>				000F
DSADRL	0BF8	DSADR<15:0>																0000
DSADRH	0BFA	—	—	—	—	—	—	—	—	DSADR<23:16>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Allocating different Page registers for read and write access allows the architecture to support data movement between different pages in data memory. This is accomplished by setting the DSRPAG register value to the page from which you want to read, and configuring the DSWPAG register to the page to which it needs to be written. Data can also be moved from different PSV to EDS pages, by configuring the DSRPAG and DSWPAG registers to address PSV and EDS space, respectively. The data can be moved between pages by a single instruction.

When an EDS or PSV page overflow or underflow occurs, EA<15> is cleared as a result of the register indirect EA calculation. An overflow or underflow of the EA in the EDS or PSV pages can occur at the page boundaries when:

- The initial address prior to modification addresses an EDS or PSV page
- The EA calculation uses Pre-Modified or Post-Modified Register Indirect Addressing; however, this does not include Register Offset Addressing

In general, when an overflow is detected, the DSxPAG register is incremented and the EA<15> bit is set to keep the base address within the EDS or PSV window. When an underflow is detected, the DSxPAG register is decremented and the EA<15> bit is set to keep the base address within the EDS or PSV window. This creates a linear EDS and PSV address space, but only when using Register Indirect Addressing modes.

Exceptions to the operation described above arise when entering and exiting the boundaries of Page 0, EDS and PSV spaces. Table 4-61 lists the effects of overflow and underflow scenarios at different boundaries.

In the following cases, when overflow or underflow occurs, the EA<15> bit is set and the DSxPAG is not modified; therefore, the EA will wrap to the beginning of the current page:

- Register Indirect with Register Offset Addressing
- Modulo Addressing
- Bit-Reversed Addressing

TABLE 4-61: OVERFLOW AND UNDERFLOW SCENARIOS AT PAGE 0, EDS and PSV SPACE BOUNDARIES(2,3,4)

O/U, R/W	Operation	Before			After		
		DSxPAG	DS EA<15>	Page Description	DSxPAG	DS EA<15>	Page Description
O, Read	[++Wn] or [Wn++]	DSRPAG = 0x1FF	1	EDS: Last page	DSRPAG = 0x1FF	0	See **Note 1**
O, Read		DSRPAG = 0x2FF	1	PSV: Last lsw page	DSRPAG = 0x300	1	PSV: First MSB page
O, Read		DSRPAG = 0x3FF	1	PSV: Last MSB page	DSRPAG = 0x3FF	0	See **Note 1**
O, Write		DSWPAG = 0x1FF	1	EDS: Last page	DSWPAG = 0x1FF	0	See **Note 1**
U, Read	[--Wn] or [Wn--]	DSRPAG = 0x001	1	PSV page	DSRPAG = 0x001	0	See **Note 1**
U, Read		DSRPAG = 0x200	1	PSV: First lsw page	DSRPAG = 0x200	0	See **Note 1**
U, Read		DSRPAG = 0x300	1	PSV: First MSB page	DSRPAG = 0x2FF	1	PSV: Last lsw page

Legend: O = Overflow, U = Underflow, R = Read, W = Write

Note 1: The Register Indirect Addressing now addresses a location in the base Data Space (0x0000-0x8000).

2: An EDS access with DSxPAG = 0x000 will generate an address error trap.

3: Only reads from PS are supported using DSRPAG. An attempt to write to PS using DSWPAG will generate an address error trap.

4: Pseudo-Linear Addressing is not supported for large offsets.

FIGURE 4-21: BIT-REVERSED ADDRESSING EXAMPLE

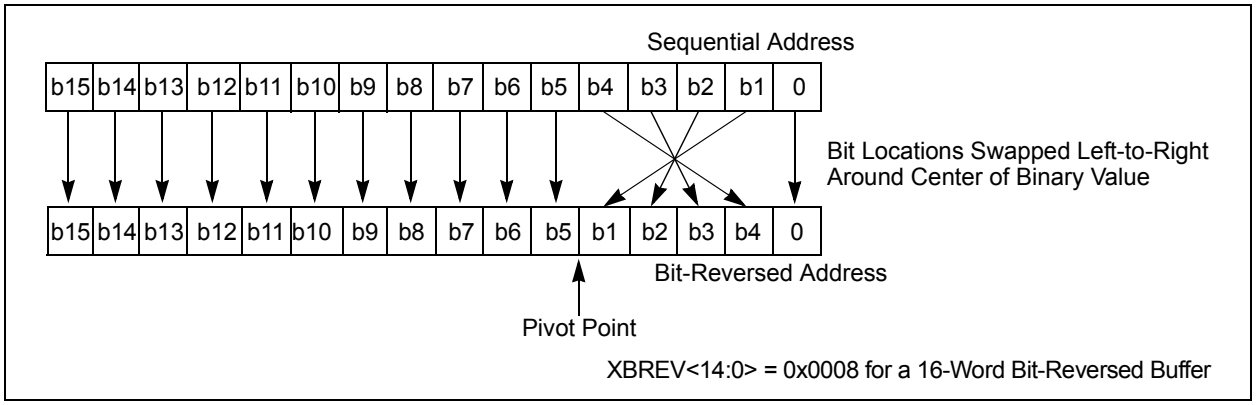


TABLE 4-64: BIT-REVERSED ADDRESSING SEQUENCE (16-ENTRY)

Normal Address					Bit-Reversed Address				
A3	**A2**	**A1**	**A0**	**Decimal**	**A3**	**A2**	**A1**	**A0**	**Decimal**
0	0	0	0	0	0	0	0	0	0
0	0	0	1	1	1	0	0	0	8
0	0	1	0	2	0	1	0	0	4
0	0	1	1	3	1	1	0	0	12
0	1	0	0	4	0	0	1	0	2
0	1	0	1	5	1	0	1	0	10
0	1	1	0	6	0	1	1	0	6
0	1	1	1	7	1	1	1	0	14
1	0	0	0	8	0	0	0	1	1
1	0	0	1	9	1	0	0	1	9
1	0	1	0	10	0	1	0	1	5
1	0	1	1	11	1	1	0	1	13
1	1	0	0	12	0	0	1	1	3
1	1	0	1	13	1	0	1	1	11
1	1	1	0	14	0	1	1	1	7
1	1	1	1	15	1	1	1	1	15

REGISTER 8-7: DMAxPAD: DMA CHANNEL x PERIPHERAL ADDRESS REGISTER(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PAD<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PAD<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **PAD<15:0>:** Peripheral Address Register bits

Note 1: If the channel is enabled (i.e., active), writes to this register may result in unpredictable behavior of the DMA channel and should be avoided.

REGISTER 8-8: DMAxCNT: DMA CHANNEL x TRANSFER COUNT REGISTER(1)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	CNT<13:8>(2)					
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CNT<7:0>(2)							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-0 **CNT<13:0>:** DMA Transfer Count Register bits(2)

Note 1: If the channel is enabled (i.e., active), writes to this register may result in unpredictable behavior of the DMA channel and should be avoided.

2: The number of DMA transfers = CNT<13:0> + 1.

11.0 I/O PORTS

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"I/O Ports"** (DS70598) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

Many of the device pins are shared among the peripherals and the parallel I/O ports. All I/O input ports feature Schmitt Trigger inputs for improved noise immunity.

11.1 Parallel I/O (PIO) Ports

Generally, a parallel I/O port that shares a pin with a peripheral is subservient to the peripheral. The peripheral's output buffer data and control signals are provided to a pair of multiplexers. The multiplexers select whether the peripheral or the associated port has ownership of the output data and control signals of the I/O pin. The logic also prevents "loop through," in which a port's digital output can drive the input of a peripheral that shares the same pin. Figure 11-1 illustrates how ports are shared with other peripherals and the associated I/O pin to which they are connected.

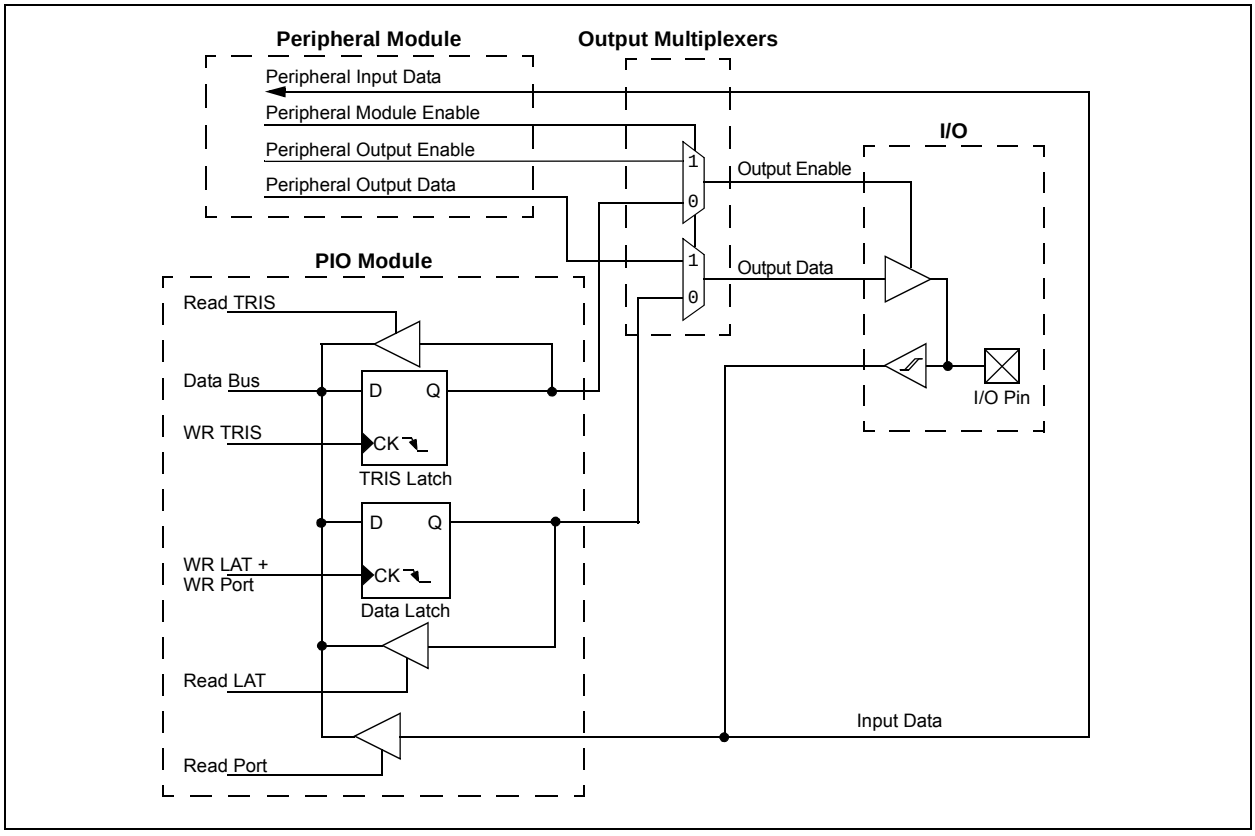
When a peripheral is enabled and the peripheral is actively driving an associated pin, the use of the pin as a general purpose output pin is disabled. The I/O pin can be read, but the output driver for the parallel port bit is disabled. If a peripheral is enabled, but the peripheral is not actively driving a pin, that pin can be driven by a port.

All port pins have eight registers directly associated with their operation as digital I/O. The Data Direction register (TRISx) determines whether the pin is an input or an output. If the data direction bit is a '1', then the pin is an input. All port pins are defined as inputs after a Reset. Reads from the Latch register (LATx) read the latch. Writes to the Latch write the latch. Reads from the port (PORTx) read the port pins, while writes to the port pins write the latch.

Any bit and its associated data and control registers that are not valid for a particular device is disabled. This means the corresponding LATx and TRISx registers and the port pin are read as zeros.

When a pin is shared with another peripheral or function that is defined as an input only, it is nevertheless regarded as a dedicated port because there is no other competing source of outputs.

FIGURE 11-1: BLOCK DIAGRAM OF A TYPICAL SHARED PORT STRUCTURE



REGISTER 11-4: RPINR7: PERIPHERAL PIN SELECT INPUT REGISTER 7

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	IC2R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	IC1R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-8 **IC2R<6:0>:** Assign Input Capture 2 (IC2) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as ‘0’

bit 6-0 **IC1R<6:0>:** Assign Input Capture 1 (IC1) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

NOTES:

15.0 OUTPUT COMPARE

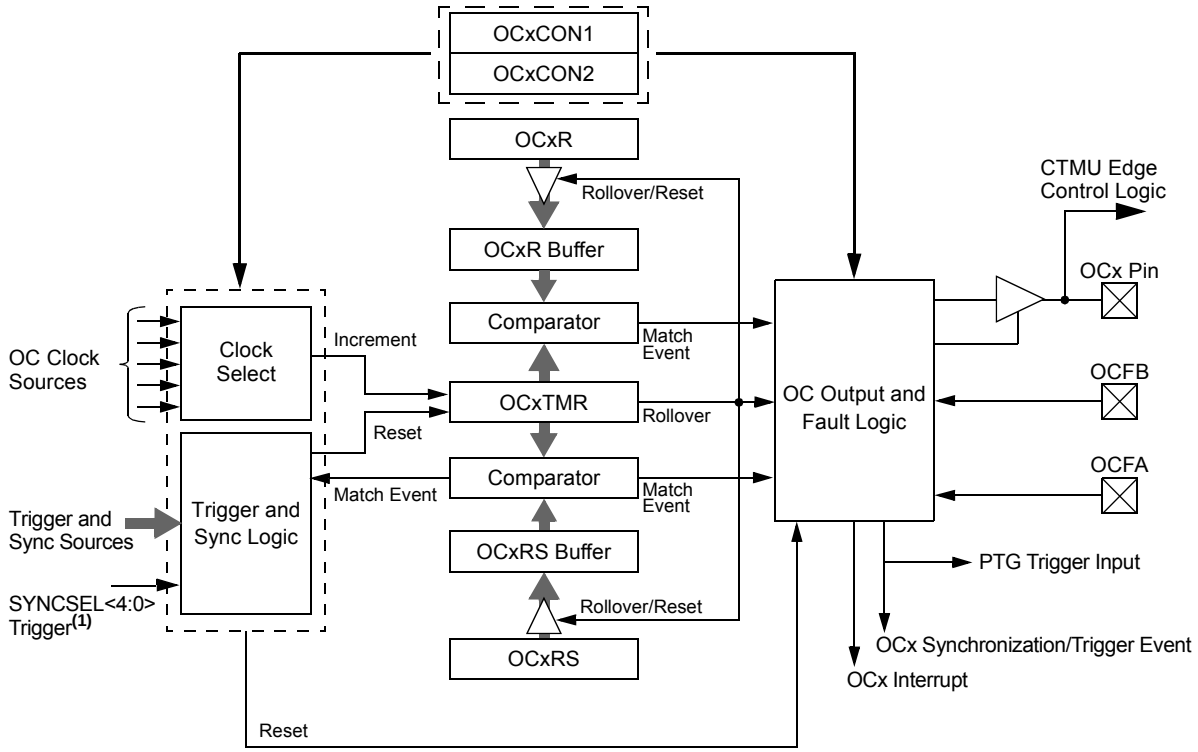
Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Output Compare"** (DS70358) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The output compare module can select one of seven available clock sources for its time base. The module compares the value of the timer with the value of one or two compare registers depending on the operating mode selected. The state of the output pin changes when the timer value matches the compare register value. The output compare module generates either a single output pulse or a sequence of output pulses, by changing the state of the output pin on the compare match events. The output compare module can also generate interrupts on compare match events and trigger DMA data transfers.

Note: See **"Output Compare"** (DS70358) in the *"dsPIC33/PIC24 Family Reference Manual"* for OCxR and OCxRS register restrictions.

FIGURE 15-1: OUTPUT COMPARE x MODULE BLOCK DIAGRAM



Note 1: The Trigger/Sync source is enabled by default and is set to Timer2 as a source. This timer must be enabled for proper OCx module operation or the Trigger/Sync source must be changed to another source option.

15.1 Output Compare Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

15.1.1 KEY RESOURCES

- **"Output Compare"** (DS70358) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

20.0 UNIVERSAL ASYNCHRONOUS RECEIVER TRANSMITTER (UART)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"UART"** (DS70582) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family of devices contains two UART modules.

The Universal Asynchronous Receiver Transmitter (UART) module is one of the serial I/O modules available in the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X device family. The UART is a full-duplex, asynchronous system that can communicate with peripheral devices, such as personal computers, LIN/J2602, RS-232 and RS-485 interfaces. The module also supports a hardware flow control option with the $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins, and also includes an IrDA® encoder and decoder.

Note: Hardware flow control using $\overline{\text{UxRTS}}$ and $\overline{\text{UxCTS}}$ is not available on all pin count devices. See the **"Pin Diagrams"** section for availability.

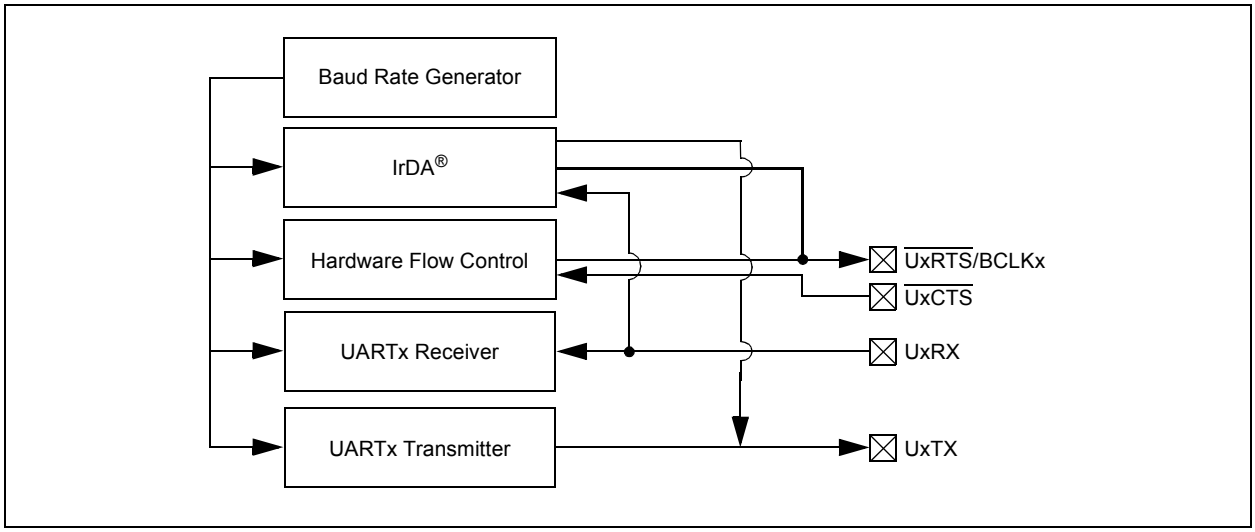
The primary features of the UARTx module are:

- Full-Duplex, 8 or 9-Bit Data Transmission through the UxTX and UxRX Pins
- Even, Odd or No Parity Options (for 8-bit data)
- One or Two Stop bits
- Hardware Flow Control Option with $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ Pins
- Fully Integrated Baud Rate Generator with 16-Bit Prescaler
- Baud Rates Ranging from 4.375 Mbps to 67 bps at 16x mode at 70 MIPS
- Baud Rates Ranging from 17.5 Mbps to 267 bps at 4x mode at 70 MIPS
- 4-Deep First-In First-Out (FIFO) Transmit Data Buffer
- 4-Deep FIFO Receive Data Buffer
- Parity, Framing and Buffer Overrun Error Detection
- Support for 9-bit mode with Address Detect (9th bit = 1)
- Transmit and Receive Interrupts
- A Separate Interrupt for all UARTx Error Conditions
- Loopback mode for Diagnostic Support
- Support for Sync and Break Characters
- Support for Automatic Baud Rate Detection
- IrDA® Encoder and Decoder Logic
- 16x Baud Clock Output for IrDA Support

A simplified block diagram of the UARTx module is shown in Figure 20-1. The UARTx module consists of these key hardware elements:

- Baud Rate Generator
- Asynchronous Transmitter
- Asynchronous Receiver

FIGURE 20-1: UARTx SIMPLIFIED BLOCK DIAGRAM



21.2 Modes of Operation

The ECAN module can operate in one of several operation modes selected by the user. These modes include:

- Initialization mode
- Disable mode
- Normal Operation mode
- Listen Only mode
- Listen All Messages mode
- Loopback mode

Modes are requested by setting the REQOP<2:0> bits (CxCTRL1<10:8>). Entry into a mode is Acknowledged by monitoring the OPMODE<2:0> bits (CxCTRL1<7:5>). The module does not change the mode and the OPMODEx bits until a change in mode is acceptable, generally during bus Idle time, which is defined as at least 11 consecutive recessive bits.

21.3 ECAN Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

21.3.1 KEY RESOURCES

- **"Enhanced Controller Area Network (ECAN™)"** (DS70353) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

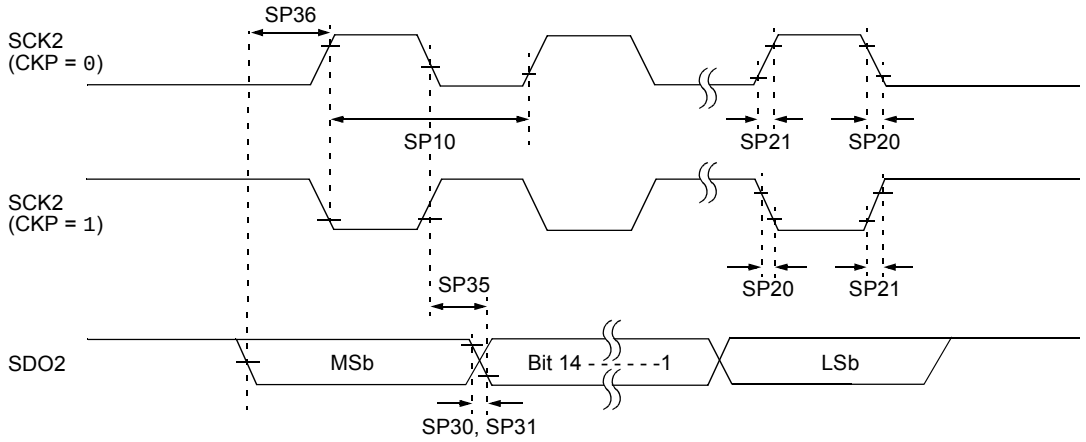
TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles(2)	Status Flags Affected
53	NEG	NEG	Acc(1)	Negate Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
		NEG	f	f = $\bar{f}$ + 1	1	1	C,DC,N,OV,Z
		NEG	f,WREG	WREG = $\bar{f}$ + 1	1	1	C,DC,N,OV,Z
		NEG	Ws,Wd	Wd = $\overline{Ws}$ + 1	1	1	C,DC,N,OV,Z
54	NOP	NOP		No Operation	1	1	None
		NOPR		No Operation	1	1	None
55	POP	POP	f	Pop f from Top-of-Stack (TOS)	1	1	None
		POP	Wdo	Pop from Top-of-Stack (TOS) to Wdo	1	1	None
		POP.D	Wnd	Pop from Top-of-Stack (TOS) to W(nd):W(nd + 1)	1	2	None
		POP.S		Pop Shadow Registers	1	1	All
56	PUSH	PUSH	f	Push f to Top-of-Stack (TOS)	1	1	None
		PUSH	Wso	Push Wso to Top-of-Stack (TOS)	1	1	None
		PUSH.D	Wns	Push W(ns):W(ns + 1) to Top-of-Stack (TOS)	1	2	None
		PUSH.S		Push Shadow Registers	1	1	None
57	PWRSAV	PWRSAV	#lit1	Go into Sleep or Idle mode	1	1	WDTO,Sleep
58	RCALL	RCALL	Expr	Relative Call	1	4	SFA
		RCALL	Wn	Computed Call	1	4	SFA
59	REPEAT	REPEAT	#lit15	Repeat Next Instruction lit15 + 1 times	1	1	None
		REPEAT	Wn	Repeat Next Instruction (Wn) + 1 times	1	1	None
60	RESET	RESET		Software device Reset	1	1	None
61	RETFIE	RETFIE		Return from interrupt	1	6 (5)	SFA
62	RETLW	RETLW	#lit10,Wn	Return with literal in Wn	1	6 (5)	SFA
63	RETURN	RETURN		Return from Subroutine	1	6 (5)	SFA
64	RLC	RLC	f	f = Rotate Left through Carry f	1	1	C,N,Z
		RLC	f,WREG	WREG = Rotate Left through Carry f	1	1	C,N,Z
		RLC	Ws,Wd	Wd = Rotate Left through Carry Ws	1	1	C,N,Z
65	RLNC	RLNC	f	f = Rotate Left (No Carry) f	1	1	N,Z
		RLNC	f,WREG	WREG = Rotate Left (No Carry) f	1	1	N,Z
		RLNC	Ws,Wd	Wd = Rotate Left (No Carry) Ws	1	1	N,Z
66	RRC	RRC	f	f = Rotate Right through Carry f	1	1	C,N,Z
		RRC	f,WREG	WREG = Rotate Right through Carry f	1	1	C,N,Z
		RRC	Ws,Wd	Wd = Rotate Right through Carry Ws	1	1	C,N,Z
67	RRNC	RRNC	f	f = Rotate Right (No Carry) f	1	1	N,Z
		RRNC	f,WREG	WREG = Rotate Right (No Carry) f	1	1	N,Z
		RRNC	Ws,Wd	Wd = Rotate Right (No Carry) Ws	1	1	N,Z
68	SAC	SAC	Acc,#Slit4,Wdo(1)	Store Accumulator	1	1	None
		SAC.R	Acc,#Slit4,Wdo(1)	Store Rounded Accumulator	1	1	None
69	SE	SE	Ws,Wnd	Wnd = sign-extended Ws	1	1	C,N,Z
70	SETM	SETM	f	f = 0xFFFF	1	1	None
		SETM	WREG	WREG = 0xFFFF	1	1	None
		SETM	Ws	Ws = 0xFFFF	1	1	None
71	SFTAC	SFTAC	Acc,Wn(1)	Arithmetic Shift Accumulator by (Wn)	1	1	OA,OB,OAB, SA,SB,SAB
		SFTAC	Acc,#Slit6(1)	Arithmetic Shift Accumulator by Slit6	1	1	OA,OB,OAB, SA,SB,SAB

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

FIGURE 30-15: SPI2 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-34: SPI2 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK2 Frequency	—	—	15	MHz	**(Note 3)**
SP20	TscF	SCK2 Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCK2 Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdiV2scH, TdiV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 66.7 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

TABLE 30-48: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	11	MHz	**(Note 3)**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS1}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS1}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH, TscL2ssH	$\overline{SS1}$ ↑ after SCK1 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 91 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

TABLE 30-57: ADC MODULE SPECIFICATIONS

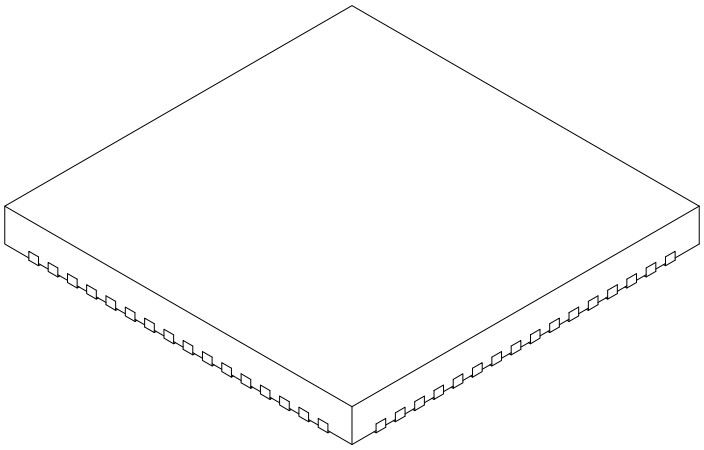
AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)[1] Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
Device Supply							
AD01	AVDD	Module VDD Supply	Greater of: VDD – 0.3 or 3.0	—	Lesser of: VDD + 0.3 or 3.6	V	
AD02	AVSS	Module VSS Supply	VSS – 0.3	—	VSS + 0.3	V	
Reference Inputs							
AD05	VREFH	Reference Voltage High	AVSS + 2.5	—	AVDD	V	VREFH = VREF+ VREFL = VREF- **(Note 1)**
AD05a			3.0	—	3.6	V	VREFH = AVDD VREFL = AVSS = 0
AD06	VREFL	Reference Voltage Low	AVSS	—	AVDD – 2.5	V	**(Note 1)**
AD06a			0	—	0	V	VREFH = AVDD VREFL = AVSS = 0
AD07	VREF	Absolute Reference Voltage	2.5	—	3.6	V	VREF = VREFH - VREFL
AD08	IREF	Current Drain	— —	— —	10 600	μA μA	ADC off ADC on
AD09	IAD	Operating Current[2]	—	5	—	mA	ADC operating in 10-bit mode **(Note 1)**
			—	2	—	mA	ADC operating in 12-bit mode **(Note 1)**
Analog Input							
AD12	VINH	Input Voltage Range VINH	VINL	—	VREFH	V	This voltage reflects Sample-and-Hold Channels 0, 1, 2 and 3 (CH0-CH3), positive input
AD13	VINL	Input Voltage Range VINL	VREFL	—	AVSS + 1V	V	This voltage reflects Sample-and-Hold Channels 0, 1, 2 and 3 (CH0-CH3), negative input
AD17	RIN	Recommended Impedance of Analog Voltage Source	—	—	200	Ω	Impedance to achieve maximum performance of ADC

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Parameter is characterized but not tested in manufacturing.

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body with 5.40 x 5.40 Exposed Pad [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		64	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		9.00 BSC	
Exposed Pad Width	E2	5.30	5.40	5.50
Overall Length	D		9.00 BSC	
Exposed Pad Length	D2	5.30	5.40	5.50
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

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TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 "Electrical Characteristics"	Removed Voltage on VCAP with respect to Vss and added Note 5 in Absolute Maximum Ratings(1). Removed Parameter DC18 (VCORE) and Note 3 from the DC Temperature and Voltage Specifications (see Table 30-4). Updated Note 1 in the DC Characteristics: Operating Current (IDD) (see Table 30-6). Updated Note 1 in the DC Characteristics: Idle Current (IIDLE) (see Table 30-7). Changed the Typical values for Parameters DC60a-DC60d and updated Note 1 in the DC Characteristics: Power-down Current (IPD) (see Table 30-8). Updated Note 1 in the DC Characteristics: Doze Current (IDOZE) (see Table 30-9). Updated Note 2 in the Electrical Characteristics: BOR (see Table 30-12). Updated Parameters CM20 and CM31, and added Parameters CM44 and CM45 in the AC/DC Characteristics: Op amp/Comparator (see Table 30-14). Added the Op amp/Comparator Reference Voltage Settling Time Specifications (see Table 30-15). Added Op amp/Comparator Voltage Reference DC Specifications (see Table 30-16). Updated Internal FRC Accuracy Parameter F20a (see Table 30-21). Updated the Typical value and Units for Parameter CTMUI1, and added Parameters CTMUI4, CTMUFV1, and CTMUFV2 to the CTMU Current Source Specifications (see Table 30-55).
Section 31.0 "Packaging Information"	Updated packages by replacing references of VLAP with TLA.
"Product Identification System"	Changed VLAP to TLA.

TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 "Electrical Characteristics" (Continued)	These SPI2 Timing Requirements were updated: • Maximum value for Parameter SP10 and the minimum clock period value for SCKx in Note 3 (see Table 30-36, Table 30-37, and Table 30-38) • Maximum value for Parameter SP70 and the minimum clock period value for SCKx in Note 3 (see Table 30-40 and Table 30-42) • The Maximum Data Rate values were updated for the SPI2 Maximum Data/Clock Rate Summary (see Table 30-43) These SPI1 Timing Requirements were updated: • Maximum value for Parameters SP10 and the minimum clock period value for SCKx in Note 3 (see Table 30-44, Table 30-45, and Table 30-46) • Maximum value for Parameters SP70 and the minimum clock period value for SCKx in Note 3 (see Table 30-47 through Table 30-50) • Minimum value for Parameters SP40 and SP41 see Table 30-44 through Table 30-50) Updated all Typical values for the CTMU Current Source Specifications (see Table 30-55). Updated Note1, the Maximum value for Parameter AD06, the Minimum value for AD07, and the Typical values for AD09 in the ADC Module Specifications (see Table 30-56). Added Note 1 to the ADC Module Specifications (12-bit Mode) (see Table 30-57). Added Note 1 to the ADC Module Specifications (10-bit Mode) (see Table 30-58). Updated the Minimum and Maximum values for Parameter AD21b in the 10-bit Mode ADC Module Specifications (see Table 30-58). Updated Note 2 in the ADC Conversion (12-bit Mode) Timing Requirements (see Table 30-59). Updated Note 1 in the ADC Conversion (10-bit Mode) Timing Requirements (see Table 30-60).